## HVC322B

## Variable Capacitance Diode for ET tuner

# **HITACHI**

ADE-208-725(Z) Rev 0 Dec. 1998

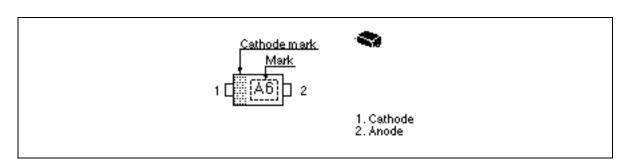
#### **Features**

- Low matching error. (ÆC/C =2.0% max)
- High capacitance ratio. (n =6.22min)
- Low series resistance. (rs=0.65½max)
- <u>Ultra small Flat Package (UFP)</u> is suitable for surface mount design.

#### **Ordering Information**

Type No.	Laser Mark	Package Code
HVC322B	A6	UFP

#### Outline





### HVC322B

### **Absolute Maximum Ratings** ( $Ta = 25^{\circ}C$ )

Item	Symbol	Value	Unit	
Peak reverse voltage	V <sub>RM</sub> * <sup>1</sup>	35	V	
Reverse voltage	V <sub>R</sub>	34	V	
Junction temperature	Tj	125	°C	
Storage temperature	Tstg	-55 to +125	°C	

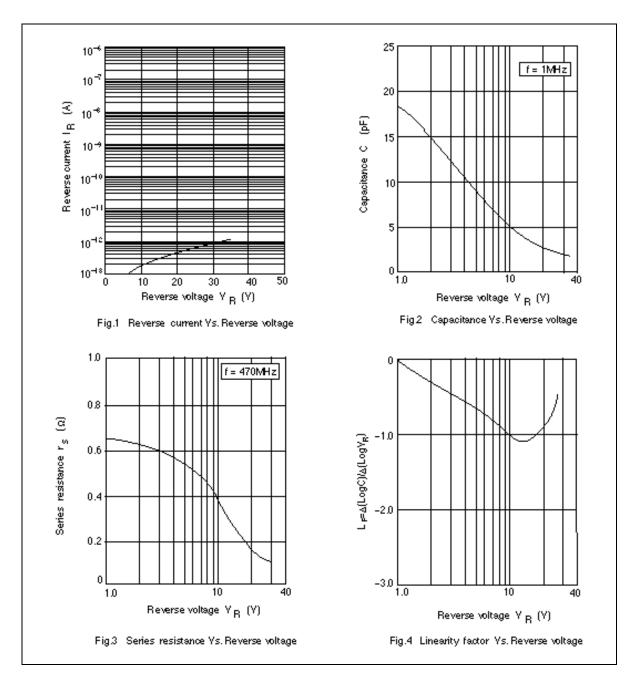
Note 1. RL=4.7K½

### **Electrical Characteristics** ( $Ta = 25^{\circ}C$ )

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse current	I <sub>R1</sub>	_	_	10	nA	V <sub>R</sub> = 32V
	I <sub>R2</sub>	_	_	100	<del>_</del>	V <sub>R</sub> = 32V, Ta= 60°C
Capacitance	C <sub>2</sub>	14.22	_	15.473	pF	V <sub>R</sub> = 2V, f = 1MHz
	C <sub>10</sub>	5.2	_	6.0		$V_R = 10V$ , $f = 1MHz$
	C <sub>17</sub>	2.8	_	3.3	<del>_</del>	$V_R = 17V$ , $f = 1MHz$
	C <sub>25</sub>	2.132	_	2.290	<del>_</del>	$V_R = 25V$ , $f = 1MHz$
Capacitance ratio	n <sub>1</sub>	6.22	_	_	_	C <sub>2</sub> /C <sub>25</sub>
	n <sub>2</sub>	1.70	_	1.96	_	C <sub>10</sub> /C <sub>17</sub>
	n <sub>3</sub>	1.04	_	_	_	C <sub>25</sub> /C <sub>28</sub>
Series resistance	r <sub>S</sub>	_	_	0.65	1/2	V <sub>R</sub> = 5V, f = 470MHz
Matching error	ÆC/C*1	_	_	2.0	%	V <sub>R</sub> = 2 to 25V, f = 1 MHz

Note 1. C.C system (Continuous Connected taping system) enable to make any 10 pcs of  $\Delta C/C$  continuous in a reel , expect extention to another group. Calculate Matching Error,

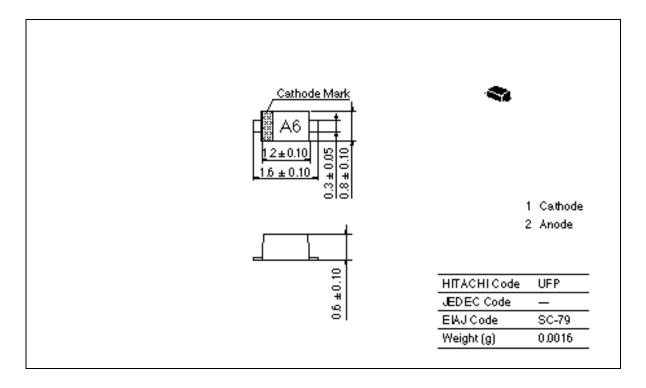
#### **Main Characteristic**



## HVC322B

## **Package Dimensions**

Unit: mm



#### **Cautions**

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